



News Release

Unisem Reports Revenue of RM365.7 million (approx. US\$84.4 million) and Net Profit of RM42.5 million (approx. US\$9.8 million) for Second Quarter 2017

Kuala Lumpur, 8 August 2017 – Unisem (M) Berhad today announced results for the second quarter ended 30 June 2017 (**2Q17**).

Unisem recorded a consolidated revenue and net profit of RM365.7 million (approx. US\$84.4 million) and RM42.5 million (approx. US\$9.8 million) respectively for 2Q17, these represent increase of 14.0 percent and 12.6 percent as compared to the revenue and net profit achieved in the corresponding quarter ended 30 June 2016 (**2Q16**) respectively.

For the six months period ended 30 June 2017 (**1H17**), the Group recorded revenue and net profit of RM726.0 million (approx. US\$165.4 million) and RM87.9 million (approx. US\$20.0 million) respectively, these represent increase of 13.7 percent in revenue and 20.4 percent in net profit as compared to the same period a year ago (**1H16**).

The increase in revenue and net profits for the current quarter and financial year to date was primarily attributable to improved profit margin arising from higher USD sales achieved coupled with the appreciation of USD/MYR exchange rate, as compared to the prevailing rate in the corresponding quarter/period a year ago.

Group's earnings before interest, tax, depreciation and amortization (EBITDA) for 2Q17 came in at about RM89.7 million (approx. US\$20.7 million), EBITDA margin was about 24.5 percent. Equipment capacity utilization averaged at about 67 percent for the Group in 2Q17. Group's capital expenditure incurred in 2Q17 was about RM41.1 million (approx. US\$9.5 million), principally for purchase of equipment for advanced packaging activities.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, the group managing director said, "We expect the performance of the Group to remain satisfactory till the end of the financial year"

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; and in Batam, Indonesia. Unisem is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com